



ニッケル (2 μm MIN.) 下地 金 (0.35 μm MIN.) GOLD (0.35 μm MIN.) OVER NICKEL (2 μm MIN.)	39-00-0300	1190G	連鎖状端子 CHAIN
銅 (0.5 μm MIN.) 下地 錫 (0.9 μm MIN.) TIN (0.9 μm MIN.) OVER COPPER (0.5 μm MIN.)	39-00-0297	1190TL	バラ端子 LOOSE
メッキ PLATING	EDP.NO.	ENG.NO.	形状 FORM

REVISED EC NO: J2009-1285 DRWN: YOSHIDAM 2008/12/19 CHKD: THARUYAMA 2008/12/19 APPR: NUKITA 2009/01/15 K	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY H. HASEGAWA	DATE '93/06/18	TITLE .093 DIA. MALE TERM.			
		10 OVER 30 UNDER	± ---	CHECKED BY H. HIRAMOTO	DATE '93/06/18	MOLEX INCORPORATED			
		30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '93/06/18				
ANGULAR	± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-1190-001	SHEET NO. 1 OF 1		